2022 IEEE/ACM International Conference on Technical Debt (TechDebt 2022)

Pittsburgh, Pennsylvania, USA 17-18 May 2022



IEEE Catalog Number: CFP22P50-POD ISBN: 978-1-6654-5211-3

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IEEE Catalog Number: CFP22P50-POD CFP22P50-POD 978-1-6654-5211-3 ISBN (Print-On-Demand): ISBN (Online): 978-1-4503-9304-1

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International Conference on Technical Debt 2022

TechDebt 2022

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